

March 1997

### Features

- This Circuit is Processed in Accordance to MIL-STD-883 and is Fully Conformant Under the Provisions of Paragraph 1.2.1.
- Fast Access Time ..... 70/90ns Max
- Low Standby Current ..... 50 $\mu$ A Max
- Low Operating Current ..... 70mA Max
- Data Retention at 2.0V ..... 20 $\mu$ A Max
- TTL Compatible Inputs and Outputs
- JEDEC Approved Pinout (2716, 6116 Type)
- No Clocks or Strobes Required
- Wide Temperature Range ..... -55 $^{\circ}$ C to +125 $^{\circ}$ C
- Equal Cycle and Access Time
- Single 5V Supply
- Gated Inputs
  - No Pull-Up or Pull-Down Resistors Required

### Description

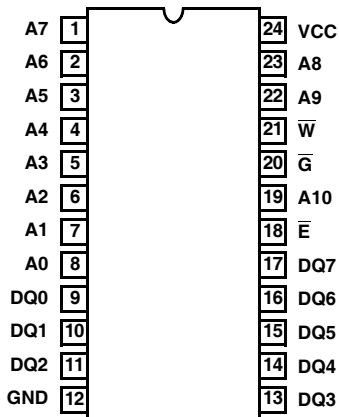
The HM-65162/883 is a CMOS 2048 x 8 Static Random Access Memory manufactured using the Intersil Advanced SAJI V process. The device utilizes asynchronous circuit design for fast cycle time and ease of use. The pinout is the JEDEC 24 pin DIP, and 32 pad 8-bit wide standard which allows easy memory board layouts flexible to accommodate a variety of industry standard PROMs, RAMs, ROMs and EPROMs. The HM-65162/883 is ideally suited for use in microprocessor based systems with its 8-bit word length organization. The convenient output enable also simplifies the bus interface by allowing the data outputs to be controlled independent of the chip enable. Gated inputs lower operating current and also eliminate the need for pull-up or pull-down resistors.

### Ordering Information

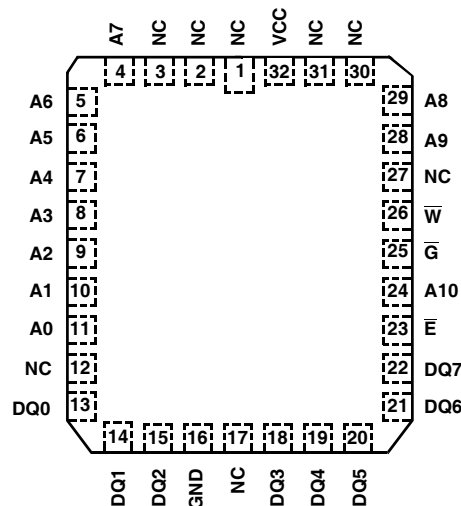
70ns/20 $\mu$ A	90ns/40 $\mu$ A	90ns/300 $\mu$ A	TEMP. RANGE	PACKAGE	PKG. NO.
HM1-65162B/883	HM1-65162/883	HM1-65162C/883	-55 $^{\circ}$ C to 125 $^{\circ}$ C	CERDIP	F24.6
HM4-65162B/883	HM4-65162/883	-	-55 $^{\circ}$ C to 125 $^{\circ}$ C	CLCC	J32.A

### Pinouts

HM-65162/883 (CERDIP)  
TOP VIEW

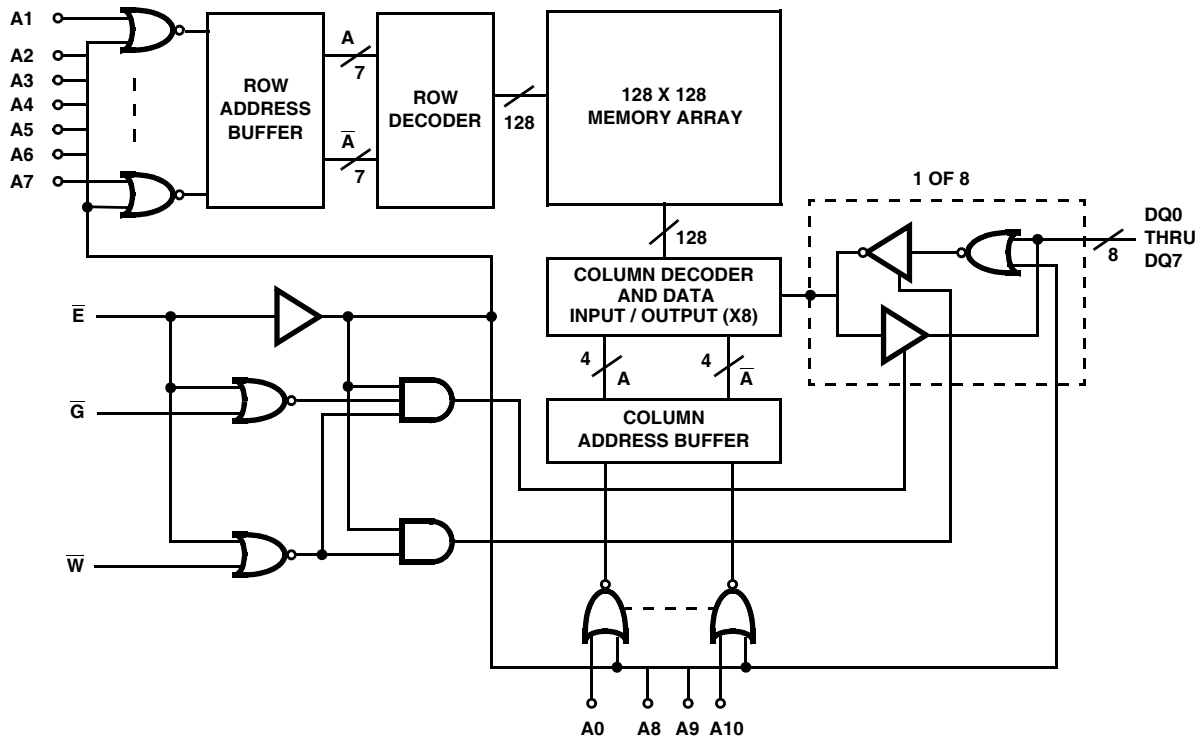


HM-65162/883 (CLCC)  
TOP VIEW



PIN	DESCRIPTION
NC	No Connect
A0 - A10	Address Input
$\bar{E}$	Chip Enable/Power Down
VSS/GND	Ground
DQ0 - DQ7	Data In/Data Out
VCC	Power (+5V)
$\bar{W}$	Write Enable
$\bar{G}$	Output Enable

Functional Diagram



# HM-65162/883

## Absolute Maximum Ratings

Supply Voltage . . . . . +7.0V  
 Input, Output or I/O Voltage . . . . . GND -0.3V to VCC +0.3V  
 Typical Derating Factor . . . . . 1.5mA/MHz Increase in ICCOP  
 ESD Classification . . . . . Class 1

## Thermal Information

Thermal Resistance  $\theta_{JA}$   $\theta_{JC}$   
 CERDIP Package . . . . . 48°C/W 8°C/W  
 CLCC Package . . . . . 66°C/W 12°C/W  
 Maximum Storage Temperature Range . . . . . -65°C to +150°C  
 Maximum Junction Temperature . . . . . +175°C  
 Maximum Lead Temperature (Soldering 10s) . . . . . +300°C

## Die Characteristics

Gate Count . . . . . 26000 Gates

*CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.*

## Operating Conditions

Operating Voltage Range . . . . . +4.5V to +5.5V  
 Operating Temperature Range . . . . . -55°C to +125°C  
 Input Low Voltage . . . . . 0V to +0.8V  
 Chip Enable High/Low Time . . . . . 40ns (Min)  
 Input High Voltage . . . . . -2.2V to VCC  
 Data Retention Supply Voltage . . . . . 2.0V to 4.5V  
 Input Rise and Fall Time . . . . . 40ns Max

**TABLE 1. 65162/883 DC ELECTRICAL PERFORMANCE SPECIFICATIONS**

Device Guaranteed and 100% Tested

PARAMETER	SYMBOL	(NOTE 1) CONDITIONS	GROUP A SUBGROUPS	TEMPERATURE	LIMITS		UNITS
					MIN	MAX	
High Level Output Voltage	VOH1	VCC = 4.5V, IO = -1.0mA	1, 2, 3	-55°C ≤ T <sub>A</sub> ≤ +125°C	2.4	-	V
Low Level Output Voltage	VOL	VCC = 4.5V, IO = 4.0mA	1, 2, 3	-55°C ≤ T <sub>A</sub> ≤ +125°C	-	0.4	V
High Impedance Output Leakage Current	IIOZ	VCC = 5.5V, $\bar{G}$ = 2.2V, or $\bar{E}$ = 2.2V, VI/O = GND or VCC	1, 2, 3	-55°C ≤ T <sub>A</sub> ≤ +125°C	-1.0	1.0	μA
Input Leakage Current	II	VCC = 5.5V, VI = GND or VCC	1, 2, 3	-55°C ≤ T <sub>A</sub> ≤ +125°C	-1.0	1.0	μA
Standby Supply Current	ICCSB1	HM-65162B/883, IO = 0mA, VCC = 5.5V, $\bar{E}$ = VCC - 0.3V	1, 2, 3	-55°C ≤ T <sub>A</sub> ≤ +125°C	-	50	μA
		HM-65162/883, IO = 0mA, VCC = 5.5V, $\bar{E}$ = VCC - 0.3V	1, 2, 3	-55°C ≤ T <sub>A</sub> ≤ +125°C	-	100	μA
		HM-65162C/883, IO = 0mA, VCC = 5.5V, $\bar{E}$ = VCC - 0.3V	1, 2, 3	-55°C ≤ T <sub>A</sub> ≤ +125°C	-	900	μA
Standby Supply Current	ICCSB	VCC = 5.5V, IO = 0mA, $\bar{E}$ = 2.2V	1, 2, 3	-55°C ≤ T <sub>A</sub> ≤ +125°C	-	8	mA
Operating Supply Current	ICCOP	VCC = 5.5V, $\bar{G}$ = 5.5V, (Note 2), f = 1MHz, $\bar{E}$ = 0.8V	1, 2, 3	-55°C ≤ T <sub>A</sub> ≤ +125°C	-	70	mA
Enable Supply Current	ICCEN	VCC = 5.5V, IO = 0mA, $\bar{E}$ = 0.8V	1, 2, 3	-55°C ≤ T <sub>A</sub> ≤ +125°C	-	70	mA
Data Retention Supply Current	ICCDR	HM-65162B/883, IO = 0mA, VCC = 2.0V, $\bar{E}$ = VCC - 0.3V	1, 2, 3	-55°C ≤ T <sub>A</sub> ≤ +125°C	-	20	μA
		HM-65162/883, IO = 0mA, VCC = 2.0V, $\bar{E}$ = VCC - 0.3V	1, 2, 3	-55°C ≤ T <sub>A</sub> ≤ +125°C	-	40	μA
		HM-65162C/883, IO = 0mA, VCC = 2.0V, $\bar{E}$ = VCC - 0.3V	1, 2, 3	-55°C ≤ T <sub>A</sub> ≤ +125°C	-	300	μA
Functional Test	FT	VCC = 4.5V (Note 3)	7, 8A, 8B	-55°C ≤ T <sub>A</sub> ≤ +125°C	-	-	-

**NOTES:**

1. All voltages referenced to device GND.
2. Input pulse levels: 0.8V to VCC - 2.0V; Input rise and fall times: 5ns (max); Input and output timing reference level: 1.5V; Output load: 1 TTL gate equivalent, CL = 50pF (min) - for CL greater than 50pF, access time by 0.15ns per pF.
3. TAVQV = TELQV + TAVEL.

**HM-65162/883**

**TABLE 2. HM-65162/883 AC ELECTRICAL PERFORMANCE SPECIFICATIONS**

Device Guaranteed and 100% Tested.

PARAMETER	SYMBOL	(NOTES 1, 2) CONDITIONS	GROUP A SUB- GROUPS	TEMPERA- TURE	LIMITS						UNITS
					HM-65162B /883		HM-65162 /883		HM-65162C /883		
					MIN	MAX	MIN	MAX	MIN	MAX	
Read/Write/ Cycle Time	(1) TAVAX	VCC = 4.5V and 5.5V	9, 10, 11	$-55^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$	70	-	90	-	90	-	ns
Address Access Time	(2) TAVQV	VCC = 4.5V and 5.5V	9, 10, 11	$-55^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$	-	70	-	90	-	90	ns
Chip Enable Access Time	(3) TELQV	VCC = 4.5V and 5.5V	9, 10, 11	$-55^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$	-	70	-	90	-	90	ns
Output Enable Access Time	(5) TGLQV	VCC = 4.5V and 5.5V	9, 10, 11	$-55^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$	-	50	-	65	-	65	ns
Chip Selection to End of Write	(11) TELWH	VCC = 4.5V and 5.5V	9, 10, 11	$-55^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$	45	-	55	-	55	-	ns
Address Setup Time	(12) TAVWL	VCC = 4.5V and 5.5V	9, 10, 11	$-55^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$	10	-	10	-	10	-	ns
Write Enable Pulse Write	(13) TWLWH	VCC = 4.5V and 5.5V	9, 10, 11	$-55^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$	40	-	55	-	55	-	ns
Write Enable Read Setup Time	(14) TWHAX	VCC = 4.5V and 5.5V	9, 10, 11	$-55^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$	10	-	10	-	10	-	ns
Data Setup Time	(17) TDVWH	VCC = 4.5V and 5.5V	9, 10, 11	$-55^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$	30	-	30	-	30	-	ns
Data Hold Time	(18) TWHDX	VCC = 4.5V and 5.5V	9, 10, 11	$-55^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$	10	-	15	-	15	-	ns
Write Enable Pulse Setup Time	(20) TWLEH	VCC = 4.5V and 5.5V	9, 10, 11	$-55^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$	40	-	55	-	55	-	ns
Chip Enable Data Setup Time	(21) TDVEH	VCC = 4.5V and 5.5V	9, 10, 11	$-55^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$	30	-	30	-	30	-	ns
Address Valid to End of Write	(22) TAVWH	VCC = 4.5V and 5.5V	9, 10, 11	$-55^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$	50	-	65	-	65	-	ns

NOTES:

1. All voltages referenced to device GND.
2. Input pulse levels: 0.8V to VCC -2.0V; Input rise and fall times: 5ns (max); Input and output timing reference level: 1.5V; Output load: 1 TTL gate equivalent, CL = 50pF (min) - for CL greater than 50pF, access time is derated by 0.15ns per pF.
3. TAVQV = TELQV + TAVEL.

## HM-65162/883

**TABLE 3. HM-65162/883 ELECTRICAL PERFORMANCE SPECIFICATIONS, AC AND DC**

PARAMETER	SYMBOL	CONDITIONS	NOTES	TEMPERATURE	LIMITS						UNITS
					HM-65162B/883		HM-65162/883		HM-65162C/883		
					MIN	MAX	MIN	MAX	MIN	MAX	
Input Capacitance	CIN	VCC = Open, F = 1MHz, All Measurements Referenced To Device Ground	1, 2	+25°C	-	10	-	10	-	10	pF
			1, 3	+25°C	-	8	-	8	-	8	pF
I/O Capacitance	CI/O	VCC = Open, F = 1MHz, All Measurements Referenced To Device Ground	1, 2	+25°C	-	12	-	12	-	12	pF
			1, 3	+25°C	-	10	-	10	-	10	pF
Chip Enable to Output ON	(4) TELQX	VCC = 4.5V and 5.5V	1	-55°C ≤ T <sub>A</sub> ≤ +125°C	5	-	0	-	5	-	ns
Output Enable to Output ON	(6) TGLQX	VCC = 4.5V and 5.5V	1	-55°C ≤ T <sub>A</sub> ≤ +125°C	5	-	5	-	5	-	ns
Chip Enable High to Output In High Z	(7) TEHQZ	VCC = 4.5V and 5.5V	1	-55°C ≤ T <sub>A</sub> ≤ +125°C	-	35	-	50	-	50	ns
Output Disable to Output in High Z	(8) TGHQZ	VCC = 4.5V and 5.5V	1	-55°C ≤ T <sub>A</sub> ≤ +125°C	-	35	-	40	-	40	ns
Output Hold from Address Change	(9) TAVQX	VCC = 4.5V and 5.5V	1	-55°C ≤ T <sub>A</sub> ≤ +125°C	5	-	5	-	5	-	ns
Write Enable to Output in High Z	(16) TWLQZ	VCC = 4.5V and 5.5V	1	-55°C ≤ T <sub>A</sub> ≤ +125°C	-	40	-	50	-	50	ns
Write Enable High to Output ON	(19) TWHQX	VCC = 4.5V and 5.5V	1	-55°C ≤ T <sub>A</sub> ≤ +125°C	0	-	0	-	0	-	ns
Output High Voltage	VOH2	VCC = 4.5V, IO = -100μA	1	-55°C ≤ T <sub>A</sub> ≤ +125°C	VCC - 0.4V	-	VCC - 0.4V	-	VCC - 0.4V	-	V

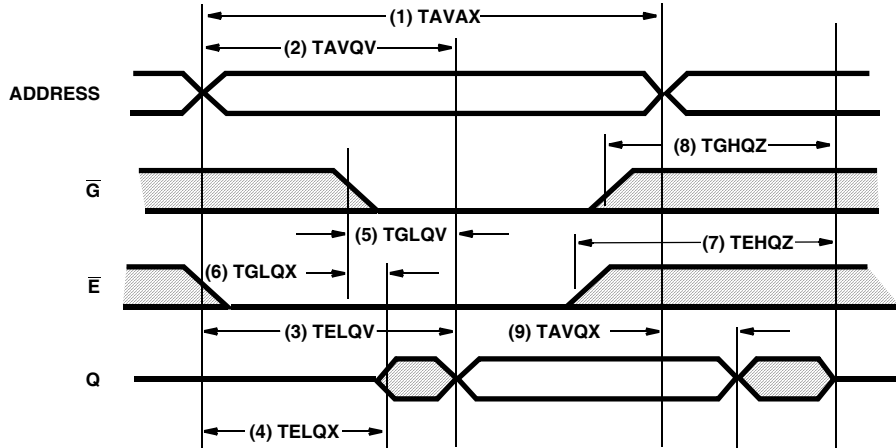
**NOTES:**

1. The parameters listed in Table 3 are controlled via design or process parameters and are not directly tested. These parameters are characterized upon initial design release and upon design changes which would affect these characteristics.
2. Applies to DIP device types only.
3. Applies to LCC device types only.

**TABLE 4. APPLICABLE SUBGROUPS**

CONFORMANCE GROUPS	METHOD	SUBGROUPS
Initial Test	100%/5004	-
Interim Test	100%/5004	1, 7, 9
PDA	100%/5004	1
Final Test	100%/5004	2, 3, 7, 8A, 8B, 10, 11
Group A	Samples/5005	1, 2, 3, 7, 8A, 8B, 9, 10, 11
Groups C & D	Samples/5005	1, 7, 9

Timing Waveforms



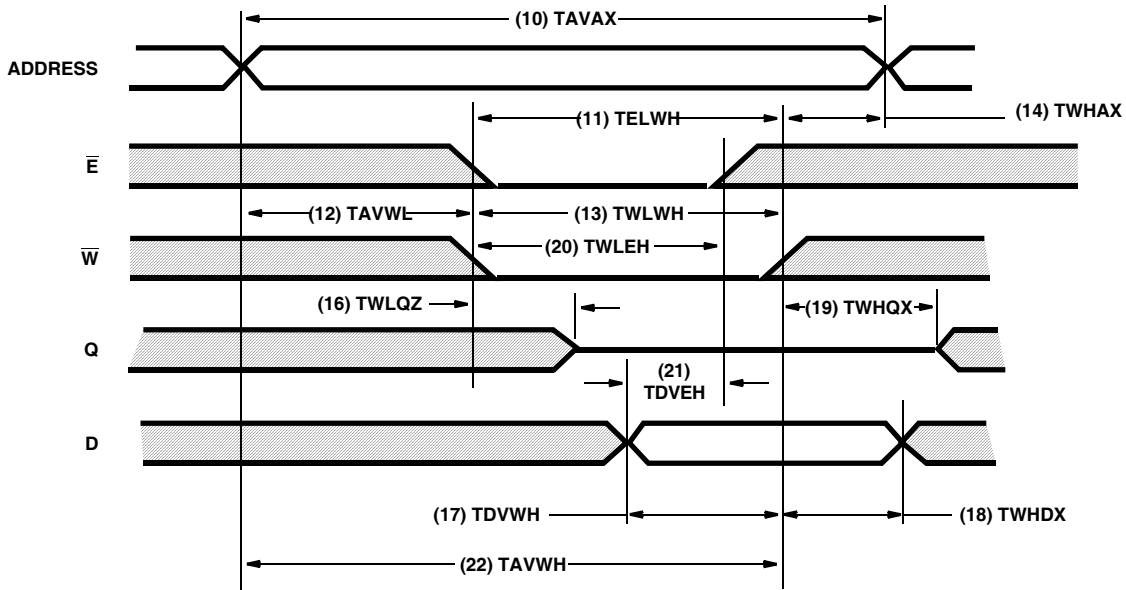
NOTE:

1.  $\bar{W}$  is High for a Read Cycle.

FIGURE 1. READ CYCLE

Addresses must remain stable for the duration of the read cycle. To read,  $\bar{G}$  and  $\bar{E}$  must be  $\leq V_{IL}$  and  $\bar{W} \geq V_{IH}$ . The output buffers can be controlled independently by  $\bar{G}$  while  $\bar{E}$  is low. To execute consecutive read cycles,  $\bar{E}$  may be tied

low continuously until all desired locations are accessed. When  $\bar{E}$  is low, addresses must be driven by stable logic levels and must not be in the high impedance state.



NOTE:

1.  $\bar{G}$  is Low throughout Write Cycle.

FIGURE 2. WRITE CYCLE I

To write, addresses must be stable,  $\bar{E}$  low and  $\bar{W}$  falling low for a period no shorter than TWLWH. Data in is referenced with the rising edge of  $\bar{W}$ , (TDVWH and TWHDX). While addresses are changing,  $\bar{W}$  must be high. When  $\bar{W}$  falls low, the I/O pins are still in the output state for a period of TWLQZ

and input data of the opposite phase to the outputs must not be applied, (Bus contention). If  $\bar{E}$  transitions low simultaneously with the  $\bar{W}$  line transitioning low or after the  $\bar{W}$  transition, the output will remain in a high impedance state.  $\bar{G}$  is held continuously low.

**Timing Waveforms (Continued)**

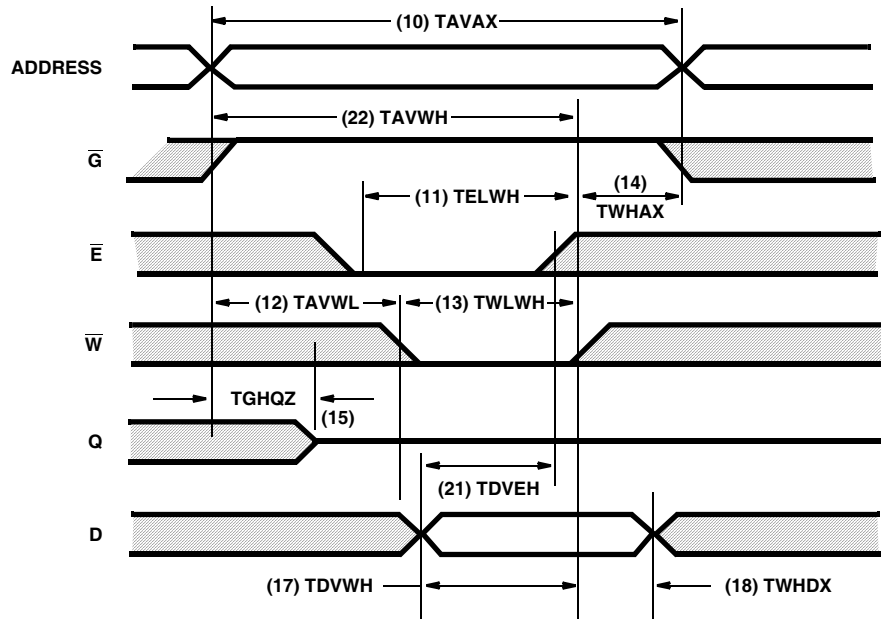


FIGURE 3. WRITE CYCLE II

In this write cycle  $\bar{G}$  has control of the output after a period, TGHQZ.  $\bar{G}$  switching the output to a high impedance state allows data in to be applied without bus contention after

TGHQZ. When  $\bar{W}$  transitions high, the data in can change after TWHDX to complete the write cycle.

**Low Voltage Data Retention**

Intersil CMOS RAMs are designed with battery backup in mind. Data retention voltage and supply current are guaranteed over temperature. The following rules ensure data retention:

1. Chip Enable ( $\bar{E}$ ) must be held high during data retention; within  $V_{CC} - 0.3V$  to  $V_{CC} + 0.3V$ .
2. On RAMs which have selects or output enables (e.g., S,  $\bar{G}$ ), one of the selects or output enables should be held in the deselected state to keep the RAM outputs high impedance, minimizing power dissipation.
3. Inputs which are to be held high (e.g.,  $\bar{E}$ ) must be kept between  $V_{CC} + 0.3V$  and 70% of  $V_{CC}$  during the power up and down transitions.
4. The RAM can begin operation > 55ns after  $V_{CC}$  reaches the minimum operating voltage (4.5V).

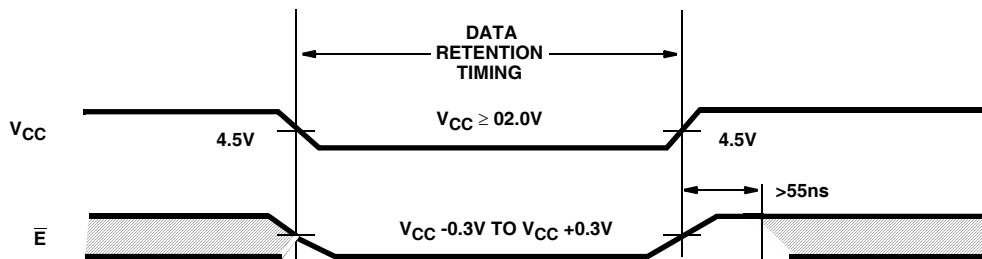
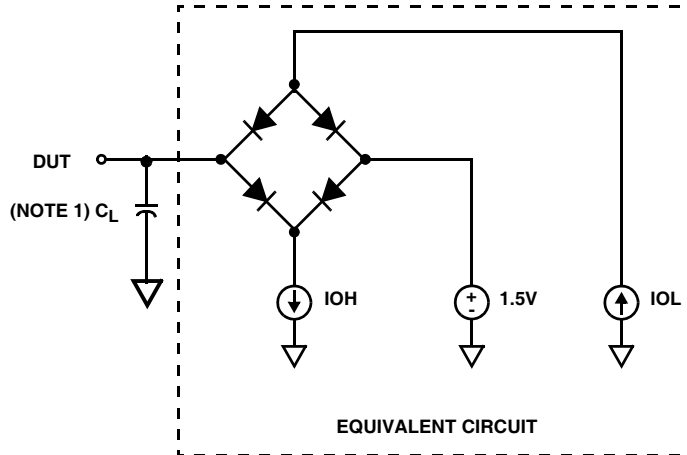


FIGURE 4. DATA RETENTION TIMING

**Test Circuit**

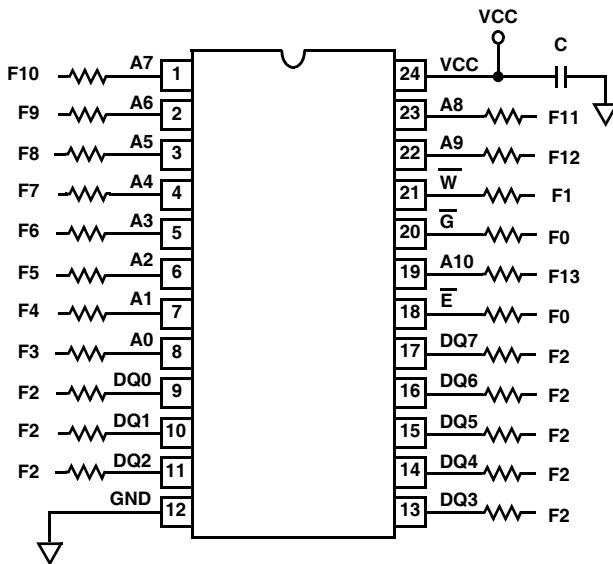


NOTE:

1. Test head capacitance includes stray and jig capacitance.

**Burn-In Circuits**

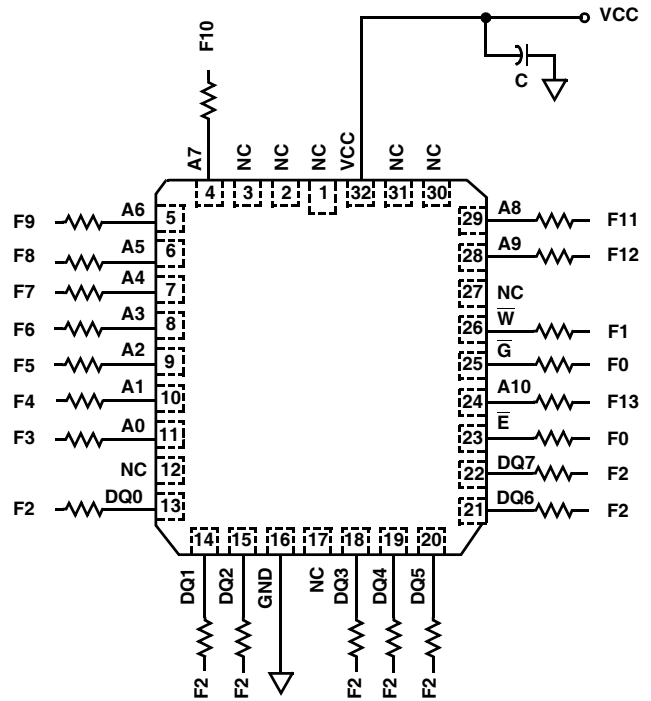
HM-65162/883  
CERDIP  
TOP VIEW



NOTES:

- All resistors 47kΩ ±5%.
- F0 = 100kHz ±10%.
- F1 = F0 ÷ 2, F2 = F1 ÷ 2, F3 = F2 ÷ 2 ... F13 = F12 ÷ 2.
- VCC = 5.5V ±0.5V.
- VIH = 4.5V ±10%.
- VIL = -0.2V to +0.4V.
- C = 0.01μF Min.

HM-65162/883  
CLCC  
TOP VIEW



NOTES:

- All resistors 47kΩ ±5%.
- F0 = 100kHz ±10%.
- F1 = F0 ÷ 2, F2 = F1 ÷ 2, F3 = F2 ÷ 2 ... F13 = F12 ÷ 2.
- VCC = 5.5V ±0.5V.
- VIH = 4.5V ±10%.
- VIL = -0.2V to +0.4V.
- C = 0.01μF Min.



# HM-65162/883

## Die Characteristics

**DIE DIMENSIONS:**  
180.3 x 194.9 x 19 ±1mils

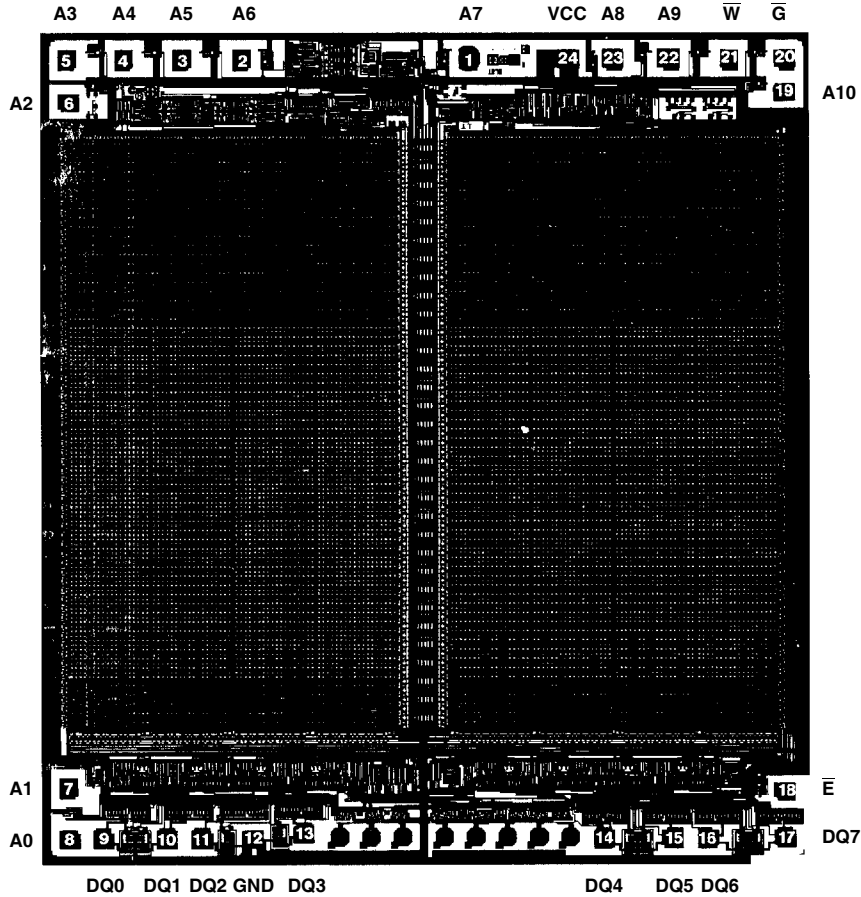
**METALLIZATION:**  
Type: Si - Al  
Thickness: 11kÅ ±2kÅ

**GLASSIVATION:**  
Type: SiO<sub>2</sub>  
Thickness: 8kÅ ±1kÅ

**WORST CASE CURRENT DENSITY:**  
1.7 x 10<sup>5</sup> A/cm<sup>2</sup>

## Metallization Mask Layout

HM-65162/883



All Intersil U.S. products are manufactured, assembled and tested utilizing ISO9000 quality systems.  
Intersil Corporation's quality certifications can be viewed at [www.intersil.com/design/quality](http://www.intersil.com/design/quality)

*Intersil products are sold by description only. Intersil Corporation reserves the right to make changes in circuit design, software and/or specifications at any time without notice. Accordingly, the reader is cautioned to verify that data sheets are current before placing orders. Information furnished by Intersil is believed to be accurate and reliable. However, no responsibility is assumed by Intersil or its subsidiaries for its use; nor for any infringements of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of Intersil or its subsidiaries.*

For information regarding Intersil Corporation and its products, see [www.intersil.com](http://www.intersil.com)